

PATENT

IN THE SPECIFICATION

Please delete the sentence appearing on page 2, lines 22-24.

Please delete the material under the "Abstract of the Disclosure" appearing on page 12, lines 1-17 and substitute the following therefor:

--An integrated circuit having at least one micromechanical element thereon is described comprising a support substrate, a sensor element electrically connected to a logic circuit, and the logic circuit electrically connected to a semiconductor visual display element. The integrated circuit may be manufactured by a process which comprises providing a support substrate, forming at least two elements selected from a first group consisting of a micromechanical sensor element, a logic circuit and a semiconductor visual display element on said support, and manufacturing at third element on said support substrate, said third element selected from a second group consisting of a micromechanical sensor element, logic circuit and a semiconductor display element, which was not selected from the first group. In one embodiment of the process of manufacture, all three of at least three elements are constructed on the support itself, preferably by a microlithographic process.--

IN THE CLAIMS

Please amend claims 1 and 4-6 to read as follows:

1. An integrated circuit with a micromechanical element comprising a support substrate supporting a sensor element, a logic circuit and a semiconductor visual display element, the sensor element electrically connected to the logic circuit, and the logic circuit being electrically connected to the semiconductor visual display element, said sensor element for providing an input to said logic circuit in response to a mechanical actuation of said sensor element.

4. The integrated circuit of claim 1 wherein said visual display element comprises an array of semiconductor pixels having diameter dimensions of less than 20